

About the joint conference of ICEP-IAAC

The JIEP was requested to hold the IMAPS All Asia Conference (IAAC) by the IMAPS. In response, the JIEP made a proposal to hold it as the joint conference with ICEP based on the discussions in the international affairs committee of the JIEP. Since it was well accepted by Asian Members such as China, Hong Kong, Korea, Taiwan, as well as US and Europe, the JIEP decided to hold ICEP 2012 as a joint

conference with the 1st IAAC. We think it is very important and meaningful that we will have the conference on electronics packaging under cooperation of various Asian members. Currently, after the 1st joint conference, Taiwan, Korea and Japan will hold the IAAC in that order.

Organizing Committee:

Vice General Chairs: S. Yamamichi, RenesasElectronics

Y. Nogami, Toray Engineering

General Chair: Y. Orii, IBM Japan

Y. Ando, Fujikura

Contact:

Secretariat of ICEP2012

http://www.jiep.or.jp/icep/

◆IEEE





Thermal Management 5. Manufacturing and Process

Sessions and Keywords:

Design, Modeling, and Reliability

6. Interconnection

Advanced Packaging

Substrate

- 3D and TSV
- 8. Printed Electronics
- . Optoelectronics
- 10. MEMS/Sensor
- 11. Self-organization/Self-assembly
- 12. Emerging Technologies 13. RF
- 14. Automotive Electronics
- 15. Energy and Environment
- 16. Metrology
- 17. Others

Abstract Deadline and Paper Submission:

A 300 words abstract to be submitted to the web site below by November 29, 2011.

Notification of acceptance by the beginning of December, 2011. Final manuscript to be submitted by February 13, 2012.